WHAT IS CLAIMED IS:

1. An epoxy resin composition comprising

a) a polyepoxide,

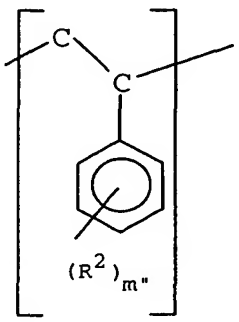
b) a cure inhibitor which is boric acid, a Lewis acid derivative of boron, an alkyl borane, a mineral acid having a nucleophilicity value "n" of greater than zero and less than 2.5 or an organic acid having a pKa value of 1 or more, but not more than 3, or a mixture of two or more thereof, and

c) more than 30 parts per 100 parts of polyepoxide, of at least one cross-linker.

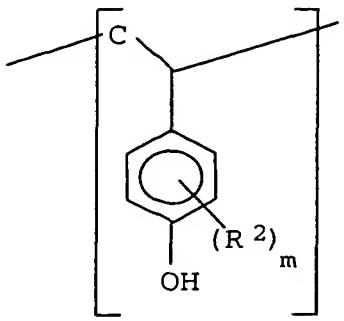
2. The epoxy resin according to Claim 1 including d) a solvent.

3. The epoxy resin composition according to Claim 1 wherein the cross-linker is an anhydride of a polycarboxylic acid.

4. The epoxy resin composition according to Claim 1 where in the cross-linker is a copolymer, containing optionally substituted styrene units of the formula



and optionally substituted hydroxystyrene units of the formula



in a ratio of 1:1 to 50:1, and wherein the total number of the said monomer units is from 3 to 10,000, m" is from 0 to 5, each R^2 independently is C_{1-3} alkyl or a halogen, and each m independently is from 0 to 4.

5. The epoxy resin composition according to Claim 1 which also comprises a bifunctional chain extension compound.

6. The epoxy resin composition according to Claim 5 wherein the bifunctional chain extension compound is bisphenol A, or tetrabromobisphenol A.

7. The epoxy resin composition according to any one of the preceding claims, which also comprises a catalytic amount of a catalyst for accelerating the reaction of the polyepoxide with the cross-linker.

8. The epoxy resin composition according to Claim 7, wherein the catalyst is a heterocyclic nitrogen compound, an amine, a phosphine, an ammonium compound, a phosphonium compound, an arsonium compound or a sulfonium compound.

9. The epoxy resin composition according to Claim 8, wherein the catalyst is an imidazole of Formula 19, or a benzimidazole of Formula 20

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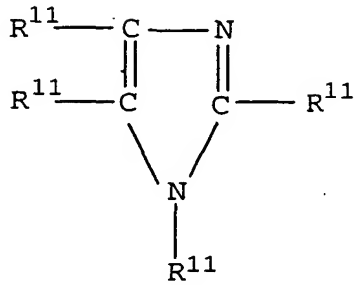

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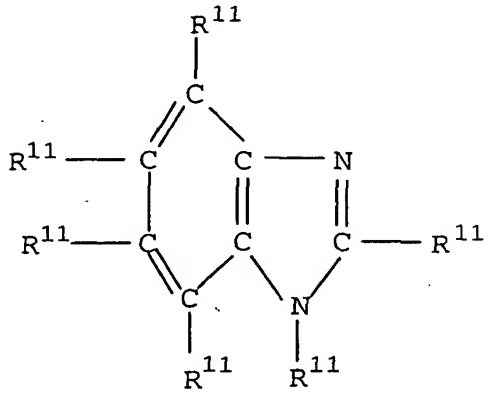
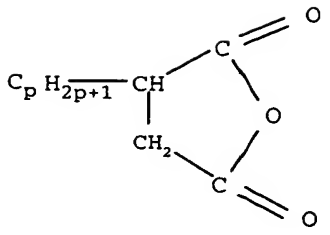


wherein each R^{11} independently is hydrogen, halogen, or an organic radical.

10. The epoxy resin composition according to Claim 9, wherein each R^{11} independently is a hydrocarbyl radical or a substituted hydrocarbyl radical.

11. The epoxy resin composition according to Claim 10, wherein each R^{11} independently is a C_1-C_5 hydrocarbyl radical substituted with an ester, ether, amide, imide, amino, halogen, or mercapto group.

12. The epoxy resin composition according to any one of Claims 1 to 11, wherein the cross-linker includes a carboxylic acid anhydride according to Formula 12, or Formula 13



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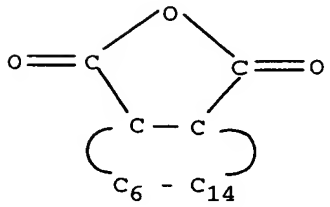

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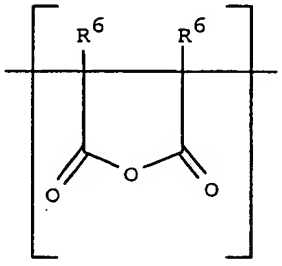
where p is from 1 to 100.

13. The epoxy resin composition according to any one of Claims 1 to 11, wherein the cross-linker includes phthalic anhydride, terphthalic anhydride, succinic anhydride, an alkyl-substituted anhydride, an alkenyl-substituted anhydride, succinic anhydride, tartaric acid anhydride, or a polyanhydride containing units of the formula

k



and

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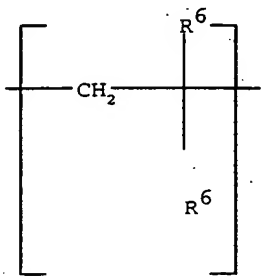
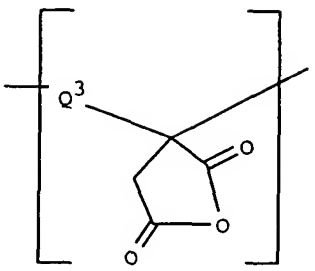


or units of the formula

k



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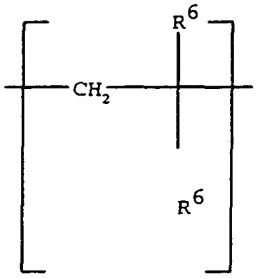
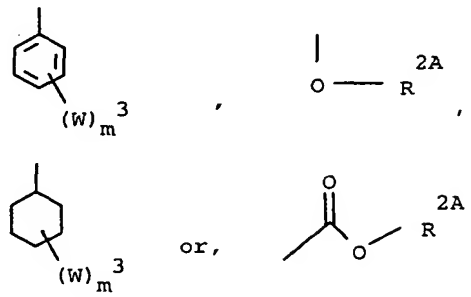


where the ratio of k to l units is from 1:1 to 50:1, the total number of monomer units k and l is from 3 to 10,000,

R^6 is hydrogen, C_{1-3} allyl, or R^{6A};

R^{6A} is:



Q^3 is C_{1-30} carbonyl, or methylene optionally substituted with one or two substituents of Formula R^{6A};

W is -OH, or -COOH;

m" is from 0 to 5; and

R^{2A} is from C_{1-30} alkyl, halogen or hydrogen.

14. An epoxy resin composition according any one of the preceding claims having a dielectric constant of 4.30, or less.

15. An epoxy resin composition according to any one of the preceding claims having a dielectric dissipation factor of less than 0.010.

16. A fiber reinforced composite article comprising a matrix including an epoxy resin according to any one of the preceding claims.

17. The fiber reinforced composite article of Claim 16, which is a laminate or a prepreg for an electric circuit.

18. An electric circuit component having an insulating coating of the epoxy resin according to any one of Claims 1 through 13.

19. A process of producing a coated article, comprising coating the article with an epoxy resin according to any one of Claims 1 through 13, and heating the coated article to cure the epoxy resin.

20. A composition useful for curing a polyepoxide resin comprising:

a) a cross-linker capable of curing with a polyepoxide at elevated temperatures; and

b) a cure inhibitor which is boric acid, a Lewis acid derivative of boron, an alkyl borane, trimethoxyboroxine, a mineral acid having a nucleophilicity value "n" of greater than zero and less than 2.5, or an organic acid having a pKa value of 1 or more, but not more than 3, or a mixture of two or more thereof.

21. A composition according to Claim 20 wherein the cross-linker is an anhydride of a polycarboxylic acid.

22. A composition according to Claim 20 wherein the cross-linker is a copolymer of styrene and/or hydroxystyrene.

23. A composition according to Claim 20 which further comprises: a bifunctional chain extender compound capable of reacting with a polyepoxide at elevated temperatures.

24. A composition according to Claim 23, which further comprises a catalytic amount of a catalyst for accelerating the reaction of the polyepoxide with the cross-linker and/or the bifunctional chain extender.

25. A composition useful to cure a polyepoxide resin according to any one of Claims 20 to 24, which further comprises a hydroxy-functional cross-linker having a functionality of 2.2 or more.